

	Type	Hits	Search Text	DBs
1	BRS	9	"61102757" or "61019154" or "60154543" or "6433412" or "6492724" or "6737755" or "6724061"	USPAT; JPO
2	BRS	294	(semiconductor or die or chip or IC) and heat near (spreader or sink or transfer) and thermal near grease and (mold\$3 or encapsulat\$3)	USPAT; JPO
3	BRS	265	(semiconductor or die or chip or IC) and heat same thermal near grease and (mold\$3 or encapsulat\$3)	USPAT; JPO
4	BRS	63	(semiconductor or die or chip or IC) and (lid or cap) same thermal near grease and (mold\$3 or encapsulat\$3)	USPAT; JPO
5	BRS	159	(semiconductor or die or chip or IC) and (lid or cap) and thermal near grease and (mold\$3 or encapsulat\$3)	USPAT; JPO
6	BRS	96	((semiconductor or die or chip or IC) and (lid or cap) and thermal near grease and (mold\$3 or encapsulat\$3)) not ((semiconductor or die or chip or IC) and (lid or cap) same thermal near grease and (mold\$3 or encapsulat\$3))	USPAT; JPO
7	BRS	339	(semiconductor or die or chip or IC) and heat and thermal near grease and (mold\$3 or encapsulat\$3)	USPAT; JPO
8	BRS	778	(semiconductor or die or chip or IC) and heat and thermal near grease	USPAT; JPO
9	BRS	439	((semiconductor or die or chip or IC) and heat and thermal near grease) not ((semiconductor or die or chip or IC) and heat and thermal near grease and (mold\$3 or encapsulat\$3))	USPAT; JPO
10	BRS	314	(semiconductor or die or chip or IC) and (lid or cap) and thermal near grease	USPAT; JPO
11	BRS	5	5977633.pn. or 5223741.pn. or 5585671.pn. or 6462410.pn. or 4748495.pn.	USPAT

	Type	Hits	Search Text	DBs
12	BRS	64	(semiconductor or die or chip or IC) and heat near (spreader or sink or transfer) and thermal near grease and (mold\$3 or encapsulat\$3) and (silicon or "Si") with chip	USPAT
13	BRS	21	(semiconductor or die or chip or IC) and heat near (spreader or sink or transfer) with (copper or "Cu") and thermal near grease and (mold\$3 or encapsulat\$3) and (silicon or "Si") with chip	USPAT
14	BRS	2440	257/738	USPAT
15	BRS	2775	257/738	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
16	BRS	20	"5785799"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
17	BRS	1570	(mold\$3 or encapsulat\$3) with curing near agent	USPAT
18	BRS	5	((mold\$3 or encapsulat\$3) with curing near agent) and (semiconductor or die or chip or IC) and heat near sink with ("Cu" or copper)	USPAT
19	BRS	9	((mold\$3 or encapsulat\$3) with curing near agent) and (semiconductor or die or chip or IC) and heat near sink with ("Cu" or copper or aluminum or "Al")	USPAT
20	BRS	0	thermal near grease with (silicon near rubber and particles)	USPAT
21	BRS	0	thermal near grease with silicon near rubber with particles	USPAT
22	BRS	3	thermal near grease with silicon near rubber	USPAT
23	BRS	0	thermal near grease same (silicon near rubber and particles)	USPAT
24	BRS	11	thermal near grease same silicon near rubber	USPAT
25	BRS	18	(thermal or heat) with grease same silicon near rubber	USPAT
26	BRS	0	(thermal or heat) with grease same (epoxy with curing near agent with catalyst with coupling near agent)	USPAT

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27	BRS	0	(thermal or heat) with grease same (epoxy with curing near agent with catalyst with coupling)	USPAT
28	BRS	10	epoxy with (mold\$3 or encapsulat\$3) and (mold\$3 or encapsulat\$3) with coefficient near thermal near expansion with "7"	USPAT
29	BRS	22	epoxy with (mold\$3 or encapsulat\$3) and (mold\$3 or encapsulat\$3) with coefficient near thermal near expansion with "5"	USPAT
30	BRS	5	epoxy with (mold\$3 or encapsulat\$3) same (mold\$3 or encapsulat\$3) with coefficient near thermal near expansion with "5"	USPAT
31	BRS	7	epoxy with (mold\$3 or encapsulat\$3) same (mold\$3 or encapsulat\$3) with coefficient near thermal near expansion with "6"	USPAT
32	BRS	1	epoxy with (mold\$3 or encapsulat\$3) same (mold\$3 or encapsulat\$3) with coefficient near thermal near expansion with "8"	USPAT
33	BRS	2	epoxy with (mold\$3 or encapsulat\$3) same (mold\$3 or encapsulat\$3) with coefficient near thermal near expansion with "9"	USPAT
34	BRS	8	epoxy with (mold\$3 or encapsulat\$3) same (mold\$3 or encapsulat\$3) with coefficient near thermal near expansion with "10"	USPAT
35	BRS	41	("Cu" or copper) with coefficient near thermal near expansion with "17"	USPAT
36	BRS	0	("Cu" or copper) with coefficient near thermal near expansion with "17" near "ppm/.degree"	USPAT
37	BRS	19	("Cu" or copper) with coefficient near thermal near expansion with "17" near ppm\$8	USPAT

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38	BRS	26	epoxy same (mold\$3 or encapsulat\$3) and (mold\$3 or encapsulat\$3) with coefficient near thermal near expansion with "10"	USPAT
39	BRS	2	epoxy same (mold\$3 or encapsulat\$3) and (mold\$3 or encapsulat\$3) with coefficient near thermal near expansion with "10" near ppm\$8	USPAT
40	BRS	1	epoxy same (mold\$3 or encapsulat\$3) and (mold\$3 or encapsulat\$3) with coefficient near thermal near expansion with "4" near ppm\$8	USPAT
41	BRS	0	epoxy same (mold\$3 or encapsulat\$3) with coefficient near thermal near expansion with "4" near ppm\$8	USPAT
42	BRS	0	epoxy same (mold\$3 or encapsulat\$3) with coefficient near thermal near expansion with "1" near ppm\$8	USPAT
43	BRS	0	epoxy with (mold\$3 or encapsulat\$3) and epoxy with coefficient near thermal near expansion with "5" near ppm\$8	USPAT
44	BRS	1	epoxy with (mold\$3 or encapsulat\$3) and epoxy with coefficient near thermal near expansion with "6" near ppm\$8	USPAT
45	BRS	0	epoxy with (mold\$3 or encapsulat\$3) and epoxy with coefficient near thermal near expansion with "7" near ppm\$8	USPAT
46	BRS	0	epoxy with (mold\$3 or encapsulat\$3) and epoxy with coefficient near thermal near expansion with "8" near ppm\$8	USPAT
47	BRS	0	epoxy with (mold\$3 or encapsulat\$3) and epoxy with coefficient near thermal near expansion with "9" near ppm\$8	USPAT
48	BRS	1	epoxy with (mold\$3 or encapsulat\$3) and epoxy with coefficient near thermal near expansion with "10" near ppm\$8	USPAT
49	BRS	0	epoxy with (mold\$3 or encapsulat\$3) and epoxy with coefficient near thermal near expansion with "11" near ppm\$8	USPAT

	Type	Hits	Search Text	DBs
50	BRS	0	epoxy with (mold\$3 or encapsulat\$3) and epoxy with coefficient near thermal near expansion with "12" near ppm\$8	USPAT
51	BRS	0	epoxy with (mold\$3 or encapsulat\$3) and epoxy with coefficient near thermal near expansion with "14" near ppm\$8	USPAT
52	BRS	3	epoxy with (mold\$3 or encapsulat\$3) and epoxy with coefficient near thermal near expansion with "15" near ppm\$8	USPAT
53	BRS	0	epoxy with (mold\$3 or encapsulat\$3) and epoxy with coefficient near thermal near expansion with "4" near ppm\$8	USPAT
54	BRS	1	epoxy with (mold\$3 or encapsulat\$3) and epoxy with coefficient near thermal near expansion with "3" near ppm\$8	USPAT
55	BRS	0	epoxy with (mold\$3 or encapsulat\$3) and epoxy with coefficient near thermal near expansion with "2" near ppm\$8	USPAT
56	BRS	4	silicon with coefficient near thermal near expansion with "2" near ppm\$8	USPAT
57	BRS	1	silicon with (chip or die) and silicon with coefficient near thermal near expansion with "2" near ppm\$8	USPAT
58	BRS	23	silicon with (chip or die) and silicon with coefficient near thermal near expansion with "3" near ppm\$8	USPAT
59	BRS	1726	257/704	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
60	BRS	2443	257/706	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
61	BRS	1515	257/717	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
62	BRS	1914	257/718	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
63	BRS	1511	257/719	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
64	BRS	1155	257/720	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
65	BRS	943	438/122	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB